

# HEAT SINK-LEAD FRAME STRUCTURE

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**Inventor:** KASEM MOHAMMED; SHINE CARL  
**Applicant:** SILICONIX INC (US)  
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- **International:** H05K7/20  
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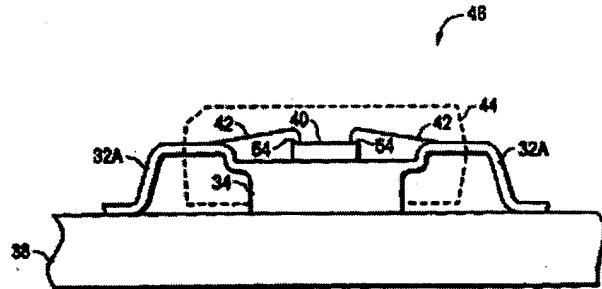
**Cited documents:**

 US5289344

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## Abstract of WO9820718

A surface mount package includes a unitary combination heat sink and lead frame, the heat sink (34) having mounted thereon a semiconductor die (40) and being mounted to a printed circuit board (38). The heat sink (34) and certain leads (32a) of the lead frame provide heat conduction paths from the die (40) to the printed circuit board (38), for highly efficient dissipation of heat.



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